

# K129

1U Passive Heat Sink

**PRODUCT SPECIFICATIONS**

## Model Number: K129

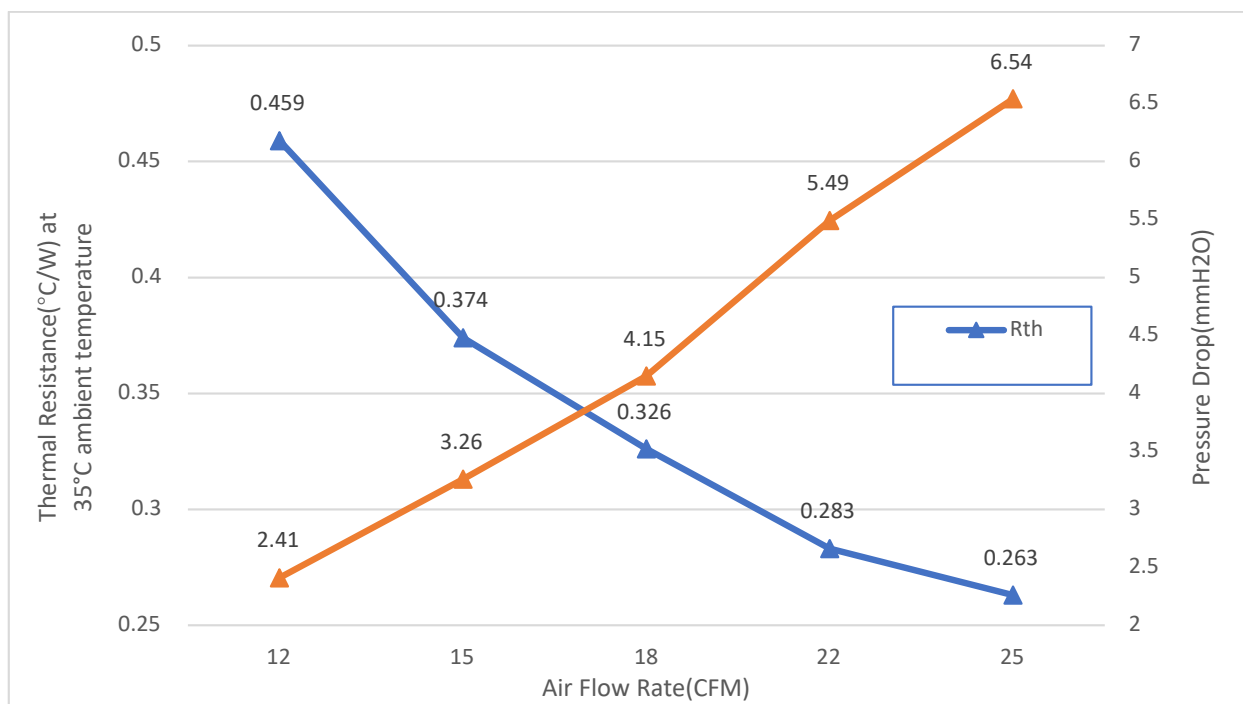
- Recommend for Intel® CPU as following
  - Intel® Xeon® Processor E3 v4 Family, Socket FCLGA 1150
  - Intel® Xeon® E Processor/Intel Core™ i7 Processor, Socket FCLGA 1151;
  - Intel® Xeon® Processor E3 Family/Intel Core™ i5 Processor, Socket LGA 1155;
  - Intel® Xeon® processor X3400, Socket LGA 1156;
  - Intel® Core™ i9 Processor, Socket FCLGA 1200;
- Passive Heat Sink for 1U Server

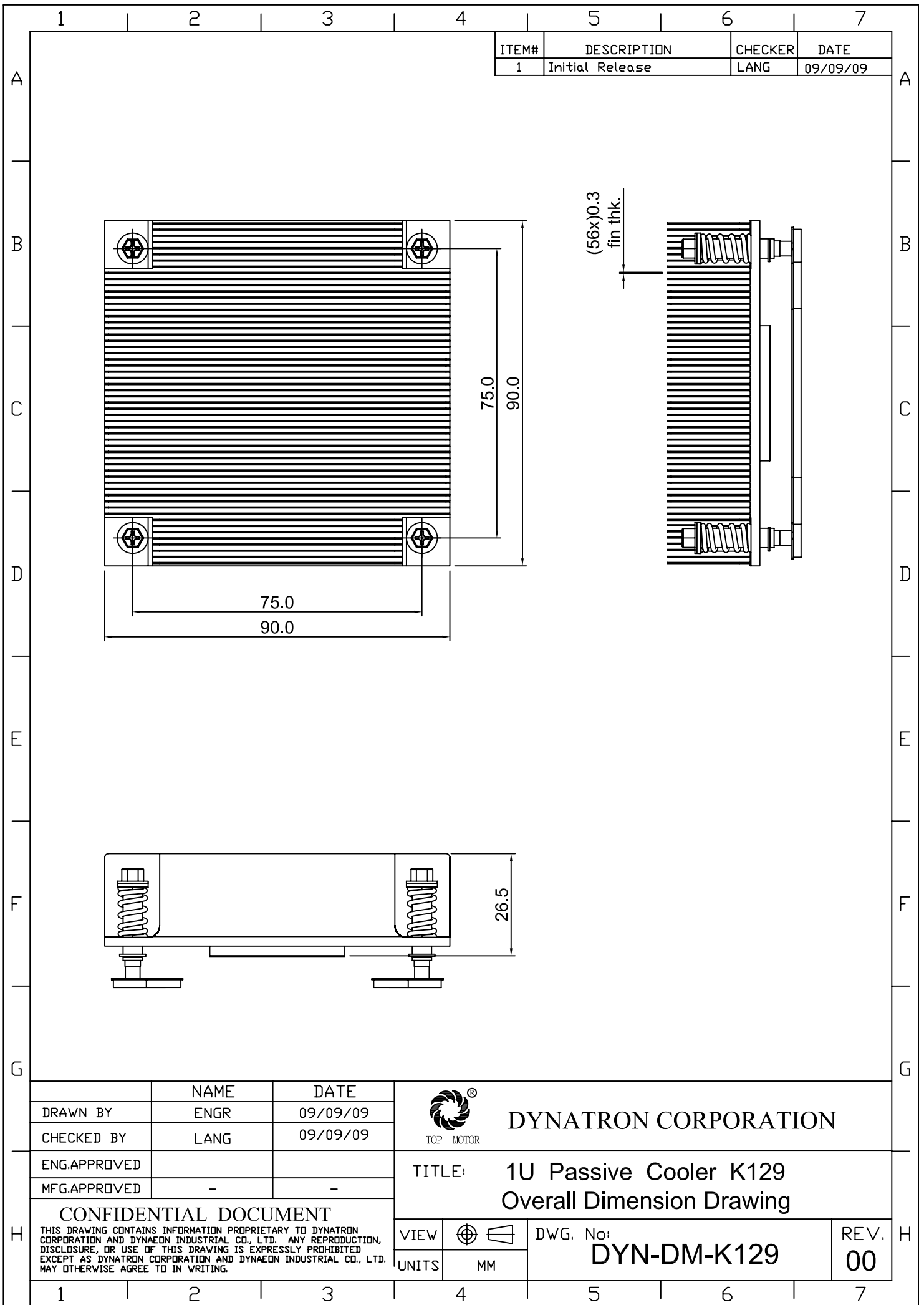
## Overall Specification

Dimension	90 x 90 x 26.5 mm
Weight	490g ±5g
Material	Copper Heat Sink with Skiving Fins
Mounting	Captive Mounting Design
Back Strip	Included
Thermal Grease	Pre-Printed with GE-Toshiba TIG830SP
TDP	Support 125 Watts CPU Power Heat Dissipation

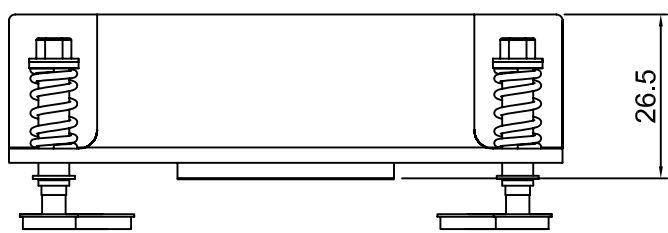
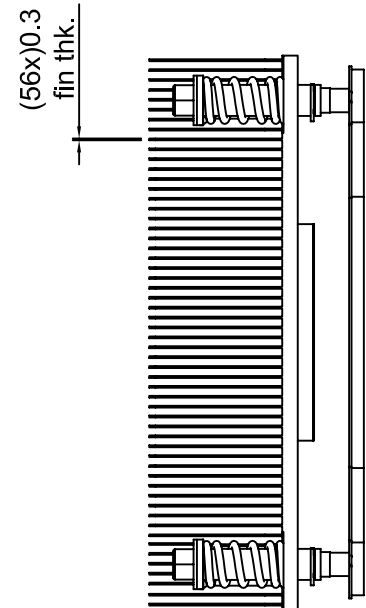
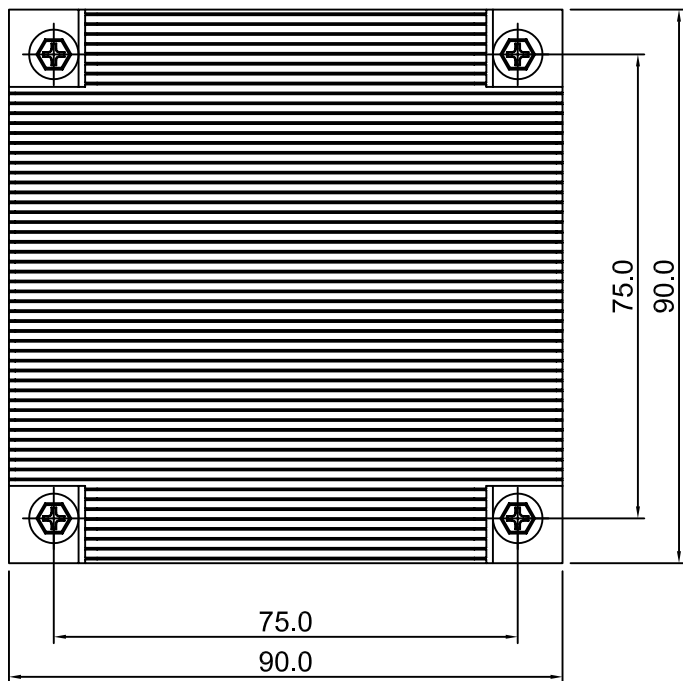
## Performance Chart: K129 Thermal Resistance

### Thermal Performance vs. Airflow





ITEM#	DESCRIPTION	CHECKER	DATE
1	Initial Release	LANG	09/09/09



	NAME	DATE
DRAWN BY	ENGR	09/09/09
CHECKED BY	LANG	09/09/09
ENG. APPROVED		
MFG. APPROVED	-	-



**DYNATRON CORPORATION**

TITLE: **1U Passive Cooler K129**  
Overall Dimension Drawing

**CONFIDENTIAL DOCUMENT**  
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VIEW	
UNITS	MM

DWG. No:  
**DYN-DM-K129**

REV.  
**00**

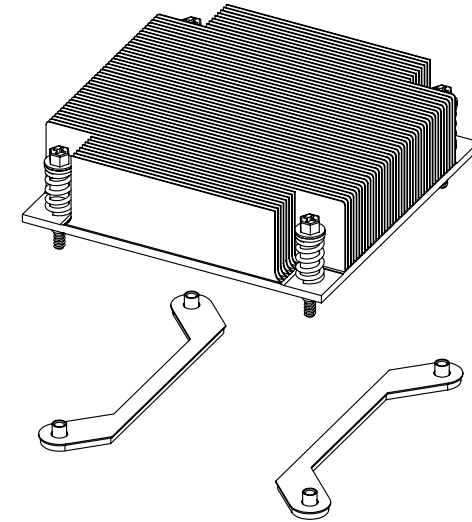
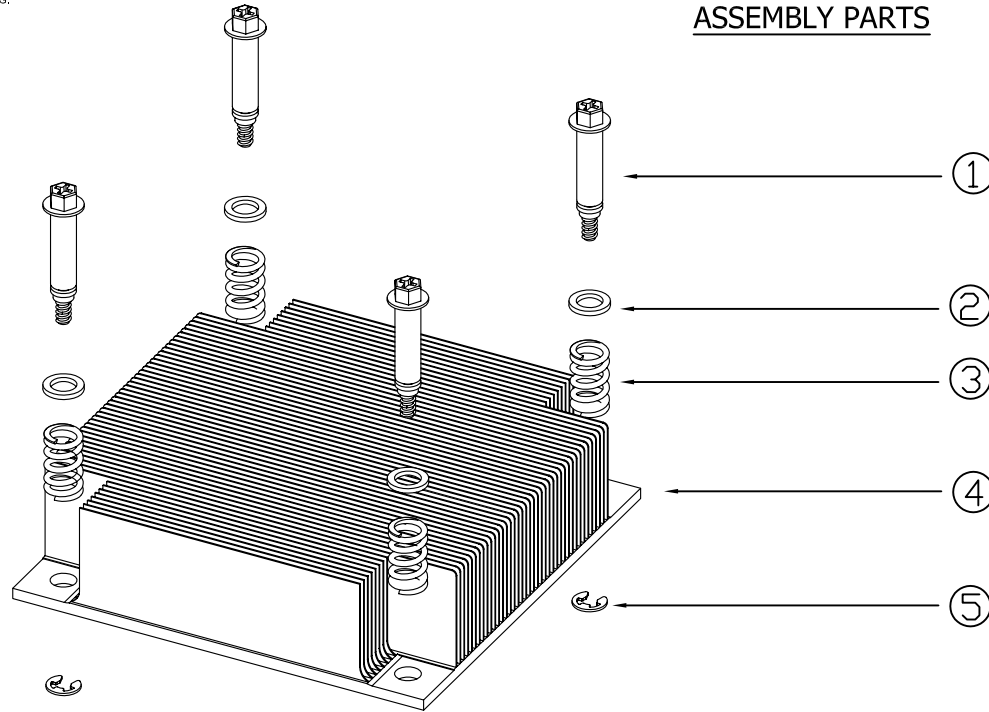
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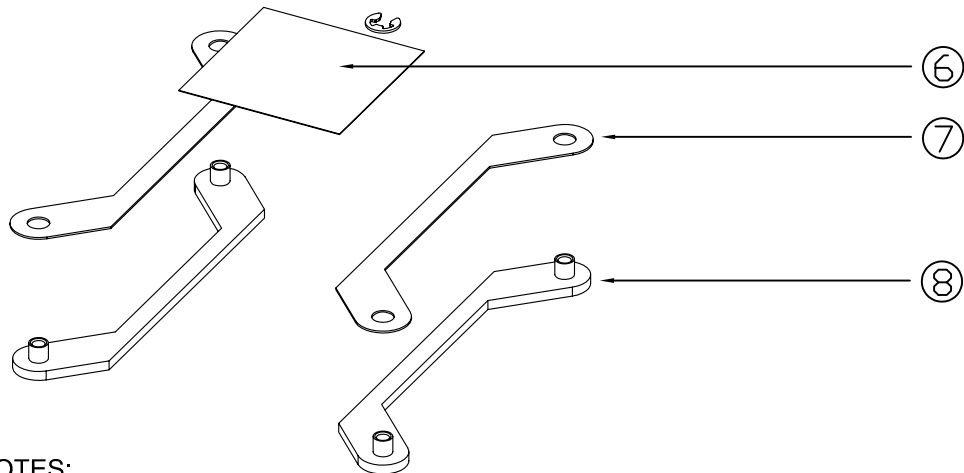
ITEM#	DESCRIPTION	CHECKER	DATE
1	Initial Release	LANG	09/09/09

ASSEMBLY PARTS

WHOLE SET OF COOLER




WHOLE PIECE OF BACKPLATE



8	BACK STRIP	SPCC	2
7	INSULATOR	FORMEX GK-17	2
6	THERMAL GREASE	TIG830SP	1
5	C-RING	STEEL	4
4	HEATSINK	COPPER 1100	1
3	SPRING	SUS 304	4
2	WASHER	STEEL	4
1	SCREW, HEATSINK	STEEL	4
ITEM NO.	DESCRIPTION	MATERIAL	QTY.

**NOTES:**

1. THE FIGURE IS FOR REFERENCE ONLY, AND NOT FOR SCALE
2. OVERALL DIMENSION: 90.0 x 90.0 x 26.5mm

DATE	NAME	 DYNATRON CORPORATION	
DRAWN 09/09/09	ENGR LANG	TITLE:	
CHECKED 09/09/09	LANG	1U Passive Cooler K129	
ENG. APPR.		BOM & Exploded Assembly Drawing	
MFG. APPR.		DWG. No: DYN-EP-K129	
QA		REV 00	
COMMENTS			